

See a clean copy of claim 21 attached hereto.

Please cancel claims 1-19, 23-26, 28-38, without prejudice for the filing of any divisional/continuation applications relating thereto.

Remarks

The finalization of the restriction requirement is noted, and the non-elected claims are herewith cancelled without prejudice to refiling thereon, in order to expedite the prosecution of the instant application.

The Examiner's comments regarding the specification are noted, and an abstract having no more than 150 words is provided herewith, as are corrections made to the disclosure, with appropriate replacement pages being provided.

The rejections of claims 20, 21, and 22 under 35 U.S.C. §103(a), over Takeda, et al. in view of Tomikawa, et al. are respectfully traversed.

With specific reference to claim 20, it will be noted that there is provided a semiconductor device with metal interconnections (wirings) formed on the bottom surface of a resin member formed by a sealing resin which seals a semiconductor element therein.

Accordingly, the present invention as required by claim 20 does not require a wiring substrate as do conventional semiconductor devices, such that the present invention is advantageous in that enables a thinner semiconductor device to be provided.

Eliminating the wiring substrate is also advantageous because the structure of the semiconductor device is simplified to achieve and improve the efficiency and reduces the cost of production of the device.

In contrast, Takeda, et al. teaches a semiconductor device that requires a wiring substrate in the form of a flexible substrate 4 with wirings formed thereon and has a semiconductor chip mounted on the wiring substrate, rather than being sealed within the wiring substrate.

Tomikawa, et al. discloses a semiconductor device which requires a wiring substrate in the form of a polyamide tape 5 with wirings formed thereon and with a semiconductor chip mounted on the wiring substrate; not sealed in the wiring substrate.

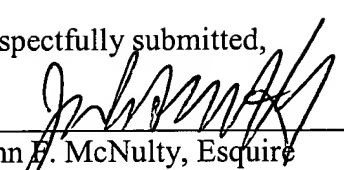
Accordingly, both of the above references are silent about, and offer no teaching of the present invention, as recited in claim 20, of a semiconductor device having metal interconnections formed on a surface of a resin member, formed by a sealing resin which seals a semiconductor element therein.

Hotta, et al. discloses an inorganic filler disbursed in a sealing resin, which corresponds to the feature defined by claim 27, but requires a wiring substrate such as 22' other than the sealing resin, in contrast to the feature defined by claim 20 herein, which does not include any wiring substrate other than a sealing resin.

In view of the above, claims 20-22 and 27 are believed to clearly patentably define over the cited references.

In view of the above, it is submitted that this application should now be in condition of allowance, and an early notification of the same would be greatly appreciated.

Respectfully submitted,



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